

## **Product Information Sheet**

<b>MATERIAL ID:</b>	<b>EPO-TEK<sup>®</sup> TV2001</b> (formerly 300-180-1-4)		
<b>Date:</b> 07/2009	Per:		
Rev: III			
Material Description:	A two component, thermally conductive, electrically insulating epoxy designed for low stress semiconductor and electronics packaging. Low Tg, moderate pot- life, snap-curing and very low modulus are a few of its traits. It is particularly suitable for bonding ferrite cores in power device plastic packaging. Excellent adhesion to PCBs, ceramics, most metals and lead-frames. Also available in a frozen syringe.		
Number of Components:	Two		
Mix Ratio by weight:	100:6		
Cure Schedule (minimum)	160°C/5 Minutes - 120°C/30 Minutes - 100°C/60 Minutes - 80°C/90 Minutes		
Specific Gravity:	Part A: 1.45 Part B: 0.99		
Pot Life:	2 Days		
Shelf Life:	One year at room temperature		
	PMF Syringe: One year at -40°C		

*NOTE:* Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before mixing and prior to use.

**MATERIAL CHARACTERISTICS:** *To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: varies as required* \* denotes test on lot acceptance basis

*Color (before cure):	Part A: White		
	Part B: Golden Yellow		
*Consistency:	Smooth paste	Die Shear @ 23°C:	$\geq$ 15 Kg / 5,100 psi
*Viscosity (23°C):		<b>Degradation Temp:</b>	466 ° <b>C</b>
@ 20 rpm	10,000 - 20,000 <b>cPs</b>	Weight Loss:	
Thixotropic Index:	1.95	@ 200°C:	0.08 %
*Glass Transition Temp:	$\geq$ 35 °C (Dynamic Cure	@ 250°C:	0.17 %
20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)		@ 300°C:	0.35 %
<b>Coefficient of Thermal</b>		<b>Operating Temp:</b>	
Below Tg:	67 x 10 <sup>-6</sup> in/in°C	Continuous:	- $55^{\circ}$ C to + $225^{\circ}$ C
Above Tg:	189 x 10 <sup>-6</sup> in/in°C	Intermittent:	- $55^{\circ}$ C to + $325^{\circ}$ C
Shore D Hardness:	45	Storage Modulus @ 23°C:	16,271 <b>psi</b>
Lap Shear @ 23°C:	> 2,000 <b>psi</b>	*Particle Size:	$\leq 20$ microns

ELECTRICAL AND THERMAL PROPERTIES:				
Thermal Conductivity:	0.40 W/mK	Dielectric Constant (1KHz):	3.42	
Volume Resistivity @ 23°C:	$\geq$ 8 x 10 <sup>12</sup> <b>Ohm-cm</b>	<b>Dissipation Factor</b> (1KHz):	0.016	

OPTICAL PROPERTIES @ 23°C:				
Spectral Transmission: N/A	Index of Refraction:	N/A		

EPOXY TECHNOLOGY, INC. 14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782 WEB SITE: www.epotek.com